EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	11	("5653575" | "5765277" | "6012502").PN. OR ("6742561"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L2	26	("3604108" | "5197650" | "5516026" | "5579980").PN. OR ("5765277"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L3	10	(L1 L2) and (cure curing cured)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26
L4	26	("3604108" | "5197650" | "5516026" | "5579980").PN. OR ("5765277"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:44
L5	2308	("156" "414" "438" "29").clas. and ((carrier backing tape) same (photopattern$4 etch$3 photocur$4) same (die circuit chip))	US-PGPUB; USPAT	OR	ON	2007/04/18 14:38
L7	633	("156" "414" "438" "29").clas. and ((carrier backing tape) same (photopattern$4 etch$3 photocur$4) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 13:56
L8	233	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern$4 etch$3 photocur$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 13:58
L9	349	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern$4 expos$3 photocur$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:02
L10	4	("156" "414" "438" "29").clas. and (((carrier backing tape) with (photopattern$4 photo-pattern$4 photo-cur$4 photocur$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:03
L11	23	("156" "414" "438" "29").clas. and (((carrier backing tape) same (photopattern$4 photo-pattern$4 photo-cur$4 photocur$4)) same (die circuit chip) same substrate) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:12

L12	6	("156" "414" "438" "29").clas. and (((carrier backing liner lining) same (photopattern$4 photo-pattern$4 photo-cur$4 photocur$4)) same (die circuit chip) same (peel$4 remov$4)) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:28
L13	45	("4630096" | "4746960" | "4827328" | "4860166" | "4866508" | "4878991" | "4884122" | "4894115" | "4907062" | "4933042" | "5049980" | "5091769" | "5111278" | "5144747" | "5250843" | "5324687" | "5426566" | "5757072").PN. OR ("6159767"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 14:16
L14	87	(((carrier backing liner lining) with (photopattern$4 photo-pattern$4 photo-cur$4 photocur$4)) same (die circuit chip) same (peel$4 remov$4)) and (vias via)	US-PGPUB; USPAT	OR	ON	2007/04/18 14:28
L15	538	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same coat$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:14
L16	67	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same (deposit$4 coat$4) same (via vias))	US-PGPUB; USPAT	OR	ON	2007/04/18 14:58
L17	86	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same (deposit$4 coat$4)) and apparatus.ab.	US-PGPUB; USPAT	OR	ON	2007/04/18 17:47
L18	17	("3785507" | "4472218" | "4526646" | "4724030" | "4797994" | "4915565" | "4990051" | "5098501" | "5270260" | "5589029" | "5725728" | "5827394" | "5871610" | "6039833").PN. OR ("6248201"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 15:07
L19	200	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same vibrat$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:14
L20	24	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same vibrat$4 same remov$4)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:19
L21	29	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same vibrat$4 same (vacuum$4 suction$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:31

L22	0	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same ((drop droplet) with (fluid water liquid)) same (vacuum$4 suction$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:33
L23	18	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same ((drop droplet)) same (vacuum$4 suction$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:32
L24	2	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same ((spray$4) with (fluid water liquid)) same (vacuum$4 suction$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:34
L25	31	("156" "414" "438" "29").clas. and (((vacuum$4 suction$4) with (die circuit chip)) same ((spray$4) with (fluid water liquid)))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:37
L26	52	("156" "414" "438" "29").clas. and (((vacuum$4 suction$4) with (die circuit chip)) same ((clean$4) with (fluid water liquid)))	US-PGPUB; USPAT	OR	ON	2007/04/18 16:40
L27	716	("156" "414" "438" "29").clas. and (substrate same ((vacuum$4 suction$4 transfer$4) same (die circuit chip))) and ((clean$4 spray$3 drop droplet) same (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:42
L28	208	("156" "414" "438" "29").clas. and (substrate same ((vacuum$4 suction$4 transfer$4) with (die circuit chip))) and ((clean$4 spray$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:42
L29	117	("156" "414" "438" "29").clas. and (substrate same ((vacuum$4 suction$4 transfer$4) with (die circuit chip))) and ((spray$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:55
L30	9	("156" "414" "438" "29").clas. and (substrate same ((vacuum$4 suction$4 transfer$4) with (die circuit chip))) and (clean$3 same (spray$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:58

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L31	175	("156" "414" "438" "29").clas. and (substrate with (die circuit chip)) and (clean$3 same (spray$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:58
L32	31	("156" "414" "438" "29").clas. and (substrate with (die circuit chip) with (bond$4 apply adhere$4 adhering attach$4)) and (clean$3 same (spray$3 drop droplet) with (fluid water liquid) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/18 16:59
L33	98	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same (deposit$4 coat$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:54
L34	14	("156" "414" "438" "29").clas. and ((transfer$4) same (solder) same adhesive same (deposit$4 coat$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:50
L35	24	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same (embed$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 18:28
L36	7	("156" "414" "438" "29").clas. and ((suction$3 vacuum$4$4) same (die circuit chip) same adhesive same (embed$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:56
L37	7	("156" "414" "438" "29").clas. and ((suction$3 vacuum$4) same (die circuit chip) same adhesive same (embed$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:57
L38	86	("156" "414" "438" "29").clas. and ((suction$3 vacuum$4) same (die circuit chip) same adhesive same (deposit$4 coat$4) same "over")	US-PGPUB; USPAT	OR	ON	2007/04/18 17:57
L39	17	("3808028" | "4627151" | "4642321" | "5030308" | "5173766" | "5446080" | "5528157" | "5536970" | "5548884").PN. OR ("5904500"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 18:04

L40	53	(US-20040252251-$ or US-20030145939-$ or US-20030177633-$ or US-20050106839-$ or US-20010001469-$ or US-20050181597-$ or US-20040038519-$ or US-20040029489-$ or US-20020013124-$ or US-20060243205-$ or US-20040154733-$ or US-20030064212-$ or US-20020170660-$ or US-20060180595-$ or US-20030039766-$ or US-20070037321-$).did. or (US-5904545-$ or US-6919641-$ or US-6653157-$ or US-7182118-$ or US-6742561-$ or US-5591295-$ or US-6533159-$ or US-6059176-$ or US-4871110-$ or US-7033842-$ or US-6957760-$ or US-5911456-$ or US-6410415-$ or US-4452557-$ or US-6551048-$ or US-4556362-$ or US-7165711-$ or US-6193136-$ or US-6869640-$ or US-7101013-$ or US-5395446-$ or US-5804507-$ or US-6657289-$ or US-4471082-$ or US-5605715-$ or US-7182830-$). did. or (US-7028397-$ or US-5765277-$ or US-6751853-$ or US-6159767-$ or US-6794040-$ or US-6427325-$ or US-6981317-$ or US-7056767-$ or US-6248201-$ or US-6291271-$ or US-5904500-$). did.	US-PGPUB; USPAT	OR	ON	2007/04/18 18:07
L41	45	40 and (vacuum$3 suction$3)	US-PGPUB; USPAT	OR	ON	2007/04/18 18:07
L47	38	("156" "414" "438" "29").clas. and ((transfer$4) same (die circuit chip) same adhesive same (anisotropic with conduct$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 18:38
L48	0	("156" "414" "438" "29").clas. and ((transfer$4) same (pixel) same adhesive same (anisotropic with conduct$4))	US-PGPUB; USPAT	OR	ON	2007/04/18 18:38
S1	5	("5545291"|"6291896"|"5545291"|"6274508"|"6281038"|"6316278"). PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 09:35
S2	2	("6731353" "6683663").PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 09:57

S3	29	("20010031514" | "3349416" | "4191800" | "4514583" | "4966442" | "5034802" | "5436744" | "5453864" | "5545291" | "5824186" | "5904545" | "6091332" | "6094138" | "6246327" | "6274508" | "6281038" | "6291896" | "6316278" | "6468638" | "6606247").PN. OR ("6731353"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:35
S4	5	("5545291" | "6274508" | "6281038" | "6316278").PN. OR ("6683663"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:36
S5	31	(S1 S2 S3 S4)	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 09:36
S6	1	("6927085").PN.	US-PGPUB; USPAT	OR	ON	2007/04/16 10:07
S7	1434	(56/539 156/556 156/559 156/560). ccls.	US-PGPUB; USPAT	OR	ON	2007/04/16 10:08
S8	80	S7 and (transfer$3 same (nozzle suction$3) same (device wafer block substrate chip))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:54
S9	11	("5653575" | "5765277" | "6012502").PN. OR ("6742561"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:20
S10	0	(transfer$3 same ((nozzle suction$3) with (multiple plurality) with (simulatneous$3) with (device wafer block substrate chip)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:34
S11	28	(transfer$3 same ((nozzle suction$3) with (multiple plurality) with (simultaneous$3) with (device wafer block substrate chip)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:53
S12	7	("20030110610" | "5695667" | "5839187" | "5840594" | "5872051" | "6759738" | "6789720").PN. OR ("7033842").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:39
S13	38	("4332341" | "4688939" | "4871110" | "5058178" | "5088639" | "5118027" | "5219117" | "5284287" | "5445313" | "5467913" | "5506385" | "5574801").PN. OR ("5695667").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:45
S14	1	"20040252251"	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 10:45

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S15	1	(transfer$3 same ((nozzle suction$3) with (multiple plurality) with (simultaneous$3) with (die)))	US-PGPUB; USPAT	OR	ON	2007/04/16 10:53
S16	12	"FSA" and (transfer$3 same (nozzle suction$3) same (device wafer block substrate chip die circuit))	US-PGPUB; USPAT	OR	ON	2007/04/16 11:09
S17	9	("4990462" | "5545291" | "5783856" | "5824186" | "5904545" | "6281038").PN. OR ("6653157"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 11:06
S18	53	"FSA" and (transfer$3 same (function$2) same (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 11:25
S19	44	"FSA" and (transport$3 same (function$2) same (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:24
S20	26	((transfer$4 transport$3) with (suction$3 vacuum$3) with (function$2) with (block))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:34
S21	1232	((transfer$4 transport$3) with (suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:35
S22	60	((transfer$4 transport$3) with (suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality) with (simultaneous$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:58
S23	13	("3940908" | "4044937" | "4423815" | "4556362" | "4915565" | "4958982" | "4978253" | "5394973" | "5888127" | "5988065" | "6006890" | "6019564" | "6283693").PN. OR ("6551048"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/16 13:46
S24	18	(US-20030145939-$ or US-20030177633-$ or US-20040252251-$).did. or (US-7182118-$ or US-6742561-$ or US-5591295-$ or US-7033842-$ or US-6957760-$ or US-6533159-$ or US-6059176-$ or US-4871110-$ or US-6919641-$ or US-5904545-$ or US-6653157-$ or US-6551048-$ or US-5911456-$ or US-4452557-$ or US-4556362-$).did.	US-PGPUB; USPAT	OR	ON	2007/04/16 13:55
S25	15	S24 and (tape adhesive)	US-PGPUB; USPAT	OR	ON	2007/04/16 13:55

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S26	0	((invert$4 flip$4) with (suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality) with (simultaneous$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 13:58
S27	43	((invert$4 flip$4) with (suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (multiple plurality))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:30
S28	346	((suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and ((eject$4 dispens$4 coat$4) same (liquid fluid) same (adhesive))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:31
S29	61	((suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4) same (liquid fluid) same (adhesive)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:48
S30	42	((suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4) same (liquid fluid) same (water)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 15:58
S31	25	((suction$3 vacuum$3) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4) same (drop droplets) same (water)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 14:49
S32	604	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4) same (liquid fluid) same (water)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:19
S33	318	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4) same (spray$3 drop droplets) same (water)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:19
S34	154	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) same (drop droplets) same (water)) same (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:21

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S35	17	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (water)) with (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:38
S36	129	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (water)))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:24
S37	283	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (liquid)) with (substrate recept$3))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:31
S38	282	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (liquid)) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:32
S39	14	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4) with (vacuum$4 suction$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (liquid)) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:42
S40	2	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (water)) with (substrate recept$3) with (transport$4 transfer$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:39
S41	5	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and ((((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (water)) with (substrate recept$3)) same (transport$4 transfer$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:38

S42	156	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (liquid fluid)) with (substrate recept$3) with (transport$4 transfer$4))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:39
S43	1	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4) with (vacuum$4 suction$4)) and (((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (fluid)) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:47
S44	25	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4) with (vacuum$4 suction$4)) and ((eject$4 dispens$4 coat$4 spray$4) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:52
S45	4	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4) with (vacuum$4 suction$4)) and ((water) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:52
S46	38	((substrate) with (device chip die wafer diode "LED" circuit) with (transfer$4 transport$4) with (vacuum$4 suction$4)) and ((liquid) with (drop droplets) with (substrate))	US-PGPUB; USPAT	OR	ON	2007/04/16 16:53
S47	4	((transfer$4 transport$3) with (suction$3 vacuum$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:10
S48	20	((transfer$4 transport$3) with (suction$3 vacuum$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:13
S49	109	((transfer$4 transport$3) same (suction$3 vacuum$3) same (circuit chip device die wafer device) same (substrate)) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:24
S50	89	S49 not S48	US-PGPUB; USPAT	OR	ON	2007/04/17 08:13

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S51	18	"156".clas. and ((transfer$4 transport$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:59
S52	13	"FSA" and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:40
S53	3	"fluidic self-assembly" and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:41
S54	1802	(fluid$3 wih self-assembly) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S55	3	(fluid$3 with self-assembly) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S56	5	(fluid$3 with self with assembl$3) and (substrate with (drop droplet spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:42
S57	215	(fluid$3 with self with assembl$3) and (substrate with (drop droplet spray$3 water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:43
S58	123	(fluid$3 with self with assembl$3) and (substrate with (drop droplet spray$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:45
S59	8	(fluid$3 with self with assembl$3) and ((substrate with (drop droplet spray$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:17
S60	21	(fluid$3 with self with assembl$3) and ((substrate with (micro-drop$3 eject$3 dispens$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:52
S61	9	(fluid$3 with self with assembl$3) and ((receptor with (micro-drop$3 eject$3 dispens$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:56
S62	2	(fluid$3 with self with assembl$3) and ((receptor with (spray$3 drop$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 08:56
S63	10	"156".clas. and ((transfer$4 transport$3) with (circuit chip device die wafer device) with (substrate)) and (substrate with (eject$3 dispens$3 micro-drop$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 08:58
S64	233	"156".clas. and ((transfer$4 transport$3) with (circuit chip device die wafer device)) and ((spray$3) with (water))	US-PGPUB; USPAT	OR	ON	2007/04/17 09:27

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S65	16	"156".clas. and ((transfer$4) with (circuit chip device die wafer device)) and ((spray$3) with (water) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:30
S66	18	"156".clas. and ((transfer$4) with (circuit chip device die wafer device)) and ((spray$3) with (clean$3) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:31
S67	7	"156".clas. and ((transfer$4) with (circuit chip device die wafer device)) and ((spray$3) with (rins$3) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:32
S68	52	"156".clas. and ((transfer$4) with (circuit chip device die wafer device)) and ((spray$3) with (fluid solvent liquid) with substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:36
S69	20	"156".clas. and ((transfer$4) same (suction$3 vacuum$3) same (circuit chip device die wafer device) same substrate) and ((spray$3) same (fluid solvent liquid water) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:38
S70	54	("29" "438" "414").clas. and ((transfer$4) same (suction$3 vacuum$3) same (circuit chip device die wafer device) same substrate) and ((spray$3) same (fluid solvent liquid water) same substrate)	US-PGPUB; USPAT	OR	ON	2007/04/17 09:48
S71	372	((transfer$4) same (circuit chip diode "LED" die wafer device) same substrate) and ((spray$3) same (fluid solvent liquid water) same substrate same (before prior))	US-PGPUB; USPAT	OR	ON	2007/04/17 09:51
S72	65	("156" "414" "438" "29").clas. and ((transfer$4) same (circuit chip diode "LED" die wafer device) same substrate) and ((spray$3) same (fluid solvent liquid water) same substrate same (before prior))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:00
S73	27	("156" "414" "438" "29").clas. and ((transfer$4) same (circuit chip diode "LED" die wafer device)) and ((spray$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer$4)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:06

S74	21	("156" "414" "438" "29").clas. and ((transfer$4) same (circuit chip diode "LED" die device semiconductor)) and ((spray$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer$4)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:11
S75	10	("156" "414" "438" "29").clas. and ((transfer$4)) and ((spray$3) same (fluid solvent liquid water) same substrate same (before prior) same transfer$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/18 13:52
S76	176	("156" "414" "438" "29").clas. and ((transfer$4)) and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/17 10:14
S77	176	("156" "414" "438" "29").clas. and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4) not S73	US-PGPUB; USPAT	OR	ON	2007/04/17 10:39
S78	268	(fluid$3 with self with assembl$3) and (((drop droplet spray$3)) same water)	US-PGPUB; USPAT	OR	ON	2007/04/17 10:17
S79	46	("156" "414" "438" "29").clas. and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4 same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:46
S80	102	((function$3 near3 block) diode "LED" pixel sensor) and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4 same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:49
S81	72	transfer$4.ab. and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4 same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:54
S82	8	electronic.ab. and ((spray$3) same (fluid solvent liquid water) same substrate same transfer$4 same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 10:55
S83	129	(((spray$3) with (fluid solvent liquid water) with substrate) same transfer$4 same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:01
S84	37	(((spray$3) with (fluid solvent liquid water) with substrate) same adhesive same (clean$3 rins$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:05
S85	268	(((spray$3) with (fluid solvent liquid water) with substrate) with (clean$3 rins$3)) and adhesive	US-PGPUB; USPAT	OR	ON	2007/04/17 11:06

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S86	141	(((spray$3) with (fluid solvent liquid water) with substrate) with (clean$3 rins$3)) and (adhesive same (transfer$3 adher$3 bond$3))	US-PGPUB; USPAT	OR	ON	2007/04/17 11:06
S87	11	("5653575" | "5765277" | "6012502").PN. OR ("6742561"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 08:41
S88	26	("3604108" | "5197650" | "5516026" | "5579980").PN. OR ("5765277"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/04/18 13:26